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**Information Technology –
Microprocessor Systems – Heterogeneous
InterConnect (HIC) (Low-Cost, Low-Latency
Scalable Serial Interconnect for
Parallel System Construction)**



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Abstract: Enabling the construction of high-performance, scalable, modular, parallel systems with low system integration cost is discussed. Complementary use of physical connectors and cables, electrical properties, and logical protocols for point-to-point serial scalable interconnect, operating at speeds of 10 200 Mb/s and at 1 Gb/s in copper and optic technologies, is described.

Keywords: flow control, encoding schemes, OMI/HIC, packet routing, parallelism, point-to-point serial scalable interconnect, protocols, routing fabric, serial links, serialization, silicon integration, switch chip, transaction layer, wormhole routing.

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